

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Dal Jae Lee	08/03/2007
Nam Ju Cho	08/03/2007
Soo-San Park	08/03/2007
Jaepil Kim	08/03/2007
Sungpil Hur	08/03/2007
Hyeong Kug Jin	08/03/2007
JongMin Han	08/03/2007
SungJae Lim	08/03/2007
HyoungChul Kwon	08/03/2007

RECEIVING PARTY DATA

Name:	STATS ChipPAC Ltd.
Street Address:	5 Yishun Street 23
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	768442

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11833646

CORRESPONDENCE DATA

Fax Number: (408)738-0881
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
 Phone: (408) 738-0592
 Email: efilings@ishimarulaw.com
 Correspondent Name: Mikio Ishimaru
 Address Line 1: Ishimaru & Zahrt LLP
 Address Line 2: 333 W. El Camino Real, Suite # 330

CH \$40.00 11833646

Address Line 4: Sunnyvale, CALIFORNIA 94087

ATTORNEY DOCKET NUMBER:

27-298

NAME OF SUBMITTER:

Mikio Ishimaru

Total Attachments: 5

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ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH MOLDING VENTS

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 5 Yishun Street 23, Singapore 768442 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

dal jae lee
 Dal Jae Lee

[Signature]
 Witness Signature
Lee, Sang Ho
 Print Witness Name
Aug 03, 2007
 Date

Aug 03 2007
 Date

[Signature]
 Witness Signature
HA SongWoo
 Print Witness Name
Aug 03, 2007
 Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Nam Ju Cho
 Nam Ju Cho

[Signature]
 Witness Signature
Lee Sang Ho
 Print Witness Name
Aug 03, 2007
 Date

Aug 03, 2007
 Date

[Signature]
 Witness Signature
HA SongWoo
 Print Witness Name
Aug 03, 2007
 Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

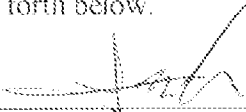
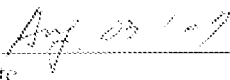
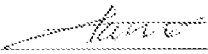

Soo-San Park
 Soo-San Park

[Signature]
 Witness Signature
Lee Sang Ho
 Print Witness Name
Aug 03, 2007
 Date


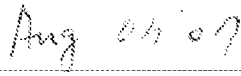
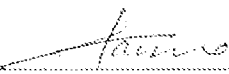
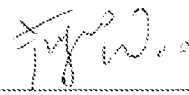
Aug 03 2007
 Date

[Signature]
 Witness Signature
HA SongWoo
 Print Witness Name
Aug 03 2007
 Date

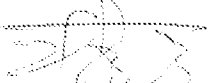
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

 ----- Jaepil Kim	 ----- Date
 ----- Witness Signature	 ----- Witness Signature
Lee Sang Ito ----- Print Witness Name	HA SongWoo ----- Print Witness Name
Aug 03 2007 ----- Date	Aug 03 2007 ----- Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

 ----- Sungpil Hur	 ----- Date
 ----- Witness Signature	 ----- Witness Signature
Lee Sang Ito ----- Print Witness Name	HA SongWoo ----- Print Witness Name
Aug 03 2007 ----- Date	Aug 03 2007 ----- Date

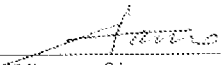
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below:



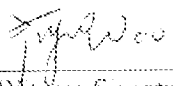
Hyeong Kug Jin

8/3/07

Date



Witness Signature



Witness Signature

Lee Sang Ho

Print Witness Name

HA SongWoo

Print Witness Name

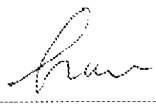
Aug. 03 2007

Date

Aug 03, 2007

Date

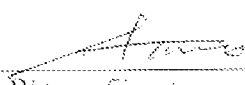
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below:



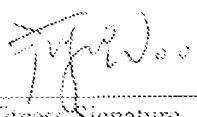
JongMin Han

Aug. 03 / 07

Date



Witness Signature



Witness Signature

Lee Sang Ho

Print Witness Name

HA SongWoo

Print Witness Name

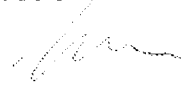
Aug. 03 2007

Date

Aug 03, 2007

Date

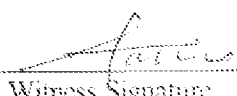
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below:



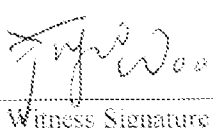
SungJae Lim

Aug. 03 / 07

Date



Witness Signature



Witness Signature

Lee Sang Ho

Print Witness Name

HA SongWoo

Print Witness Name


Aug 03 2007

Date

Aug 03, 2007

Date

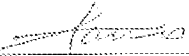
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



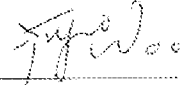
HyoungChul Kwon

Aug 03/07

Date



Witness Signature



Witness Signature

Lee Sung Ho

Print Witness Name

MA SongWoo

Print Witness Name

Aug 03 2007

Date

Aug 03 2007

Date